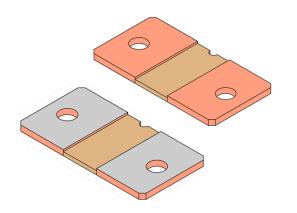




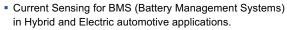
Low Ohmic EB Welded Precision Resistor



Features

- High Conductivity Copper Terminals
- Excellent Long Term Stability
- RoHS and REACH Compliant
- AEC-Q200 Compliant
- Customised versions available on request
- Tinned Terminals available on request

Applications



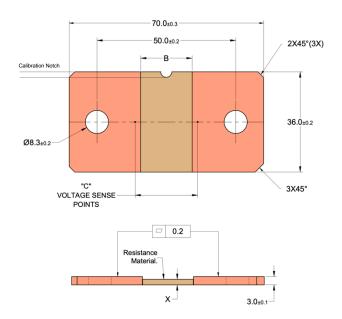
- Current Sensing for bus bars
- Current Sensing for welding equipment





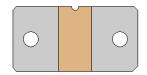


| Technical Data | | | | | |
|---|---|---------|--|--|--|
| Resistance Value | 0.025 | (mΩ) | | | |
| Tolerance (R) | 5% ,10% (+/- 10% for 0.025mΩ) | (%) | | | |
| TCR - Temperature Coefficient of Resistance Alloy (20-60°C) | < ± 10 (Copper Manganese Alloys) | (ppm/K) | | | |
| TOD (20 60%) | $<$ \pm 150 for 0.025, 0.035, 0.05 m Ω | (ppm/K) | | | |
| TCR (20-60°C) | $<$ ± 75 for 0.1 m Ω | | | | |
| Applicable Temperature Range | - 55 to +170 | °C | | | |
| Power Rating | 36 | W | | | |
| Inductance | < 3 | nH | | | |
| Thermal EMF | <1 | μV/ºC | | | |
| Stability Deviation | < 0.5 after 2000 Hours, T _t *= 110°C | % | | | |
| * T _t = Terminal Temperature | < 1.0 after 2000 Hours, T _t *= 140°C | | | | |



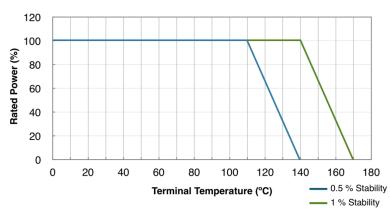
Tinned Variant

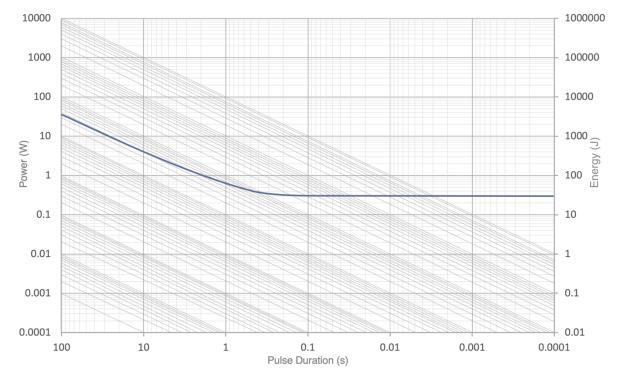
- RoHS Compliant Plating
- Sn: 2.5 to 8 µm
- Ni: 0.5 to 4 µm Inter-liner
- Base Material: C102 CuOF Half-Hard
- Available without Ni inter-liner on request



Low Ohmic EB Welded Precision Resistor

Power Derating Curve R: $0.1m\Omega$





Maximum Pulse Energy Curve

Packaging Options

| Bulk Packaging | Tray Packaging |
|---|--------------------|
| Vacuum sealed in plastic bags with dry nitrogen | 15 Shunts per tray |



Low Ohmic EB Welded Precision Resistor

| SBZ 7036 | | | | | | |
|----------------------|--------------------------|-----------------------------|-----------------------------|-----------------------------|------------------------|--|
| Part Code | Resistance Value (mΩ) | Dimension X +/-0.20 (mm) | Dimension B +/-0.50 (mm) | Dimension C +/-0.20 (mm) | Resistance Alloy | |
| SBZ-7036-CM2-R000025 | 0.025 | 2.20 | 4.50 | 7.70 | Copper Manganese Alloy | |
| SBZ-7036-CM2-R000035 | 0.035 | 2.20 | 6.20 | 9.40 | Copper Manganese Alloy | |
| SBZ-7036-CM2-R00005 | 0.05 | 2.20 | 9.00 | 12.20 | Copper Manganese Alloy | |
| SBZ-7036-CM2-R0001 | 0.10 | 2.00 | 16.50 | 19.70 | Copper Manganese Alloy | |

Performance:

| Type of Test | Reference STD | Test Specifications | Acceptance Criteria |
|------------------------------|-------------------------|---|--|
| High Temperature Exposure | MIL-STD-202 Method 108 | 1000 hrs. @ T=170°C.Unpowered. | ΔR +/-1% |
| Temperature Cycling | JESD22 Method JA-104 | -55°C to 150°C, 1000 Cycles, 30 minutes at each extreme | ΔR +/-0.5% |
| Biased Humidity | MIL-STD-202 Method 103 | 85°C & 85RH with 10% operating power, 1000 hrs. | ΔR +/-0.5% |
| Operational Life | MIL-STD-202 Method 108 | 125°C at rated power, 1000 hrs. | ΔR +/-1% |
| External Visual | MIL-STD-883 Method 2009 | Visual inspection | Visual |
| Physical Dimension | JESD22 Method JB-100 | Dimensional inspection as per internal specifications | Shall confirm within tolerance limits |
| Resistance to Solvents | MIL-STD-202 Method 215 | Clean with Aqueous Chemical | Marking shall be legible (if applicable) |
| Mechanical Shock | MIL-STD-202 Method 213 | 100g for 6ms, Half Sine | ΔR +/-0.2% |
| Vibration | MIL-STD-202 Method 204 | 5g for 20 minutes, 12 cycles each of 3 orientations.10-2000Hz | ΔR +/-0.2% |
| Resistance to Soldering Heat | MIL-STD-202 Method 210 | Solder Temp. 260°C, Time 10 seconds | ΔR +/-0.5% |
| Solderability | J-STD-002E | As per IPC J-STD-002E | >95% Coverage in 10x Magnification |
| Electrical Characterization | User Specification | Resistance as defined | Shall confirm within tolerance limits |
| Short Time Over Load | | 5x Rated Power for 5 seconds | ΔR +/-1% |
| Low Temperature Storage | | -65°C for 24 hrs. | ΔR +/-0.2% |



Low Ohmic EB Welded Precision Resistor

Example of Ordering Code: SBZ-7036-CM2-R0001-5-U-BK

(Example: 0.1mΩ SBZ 7036, un-plated terminals, shipped in bulk packing)

